

Specifications

Designed to support applications such as: SOHO (ADSL Modems), LAN-on-Motherboard (LOM), Hub and Switches. Meets IEEE 802.3 specification.

Materials:

- Housing: Thermoplastic UL94V-0
- Contact/Shield: Copper Alloy
- Shield Plating: Nickel
- Contact Plating: Gold 6μ" min. in contact area
- Wave solder tip temperature: 265°C Max for 5 Sec Max

Electrical Specifications @25°C

Operating Temperature Range: 0°C to 70°C
Turn Ratio (±2%):

$$TX = 1CT:1, RX = 1CT:1$$

Inductance OCL:

350μH Min @ 100KHz, 0.1V, 8mA

Insertion Loss:

-1.0dB Max @ 1.0-65MHz

Return Loss: (@100Ω ± 15Ω)

- 18dB Min @ 1.0-10MHz
- 14dB Min @ 10-30MHz
- 12dB Min @ 30-60MHz
- 10dB Min @ 60-80MHz

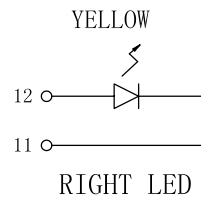
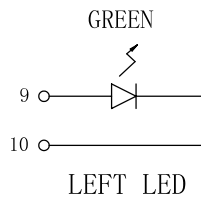
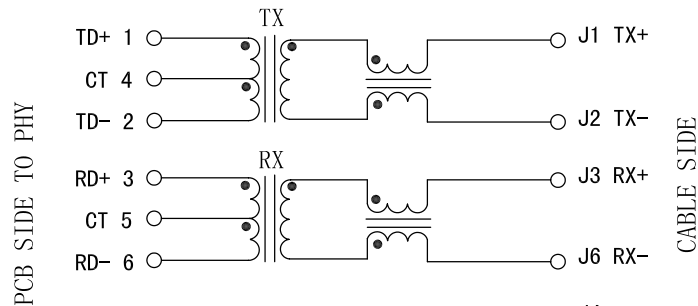
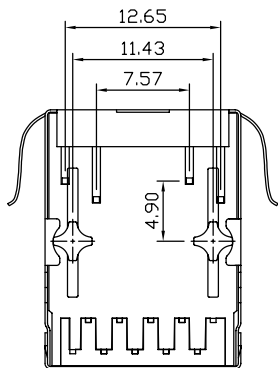
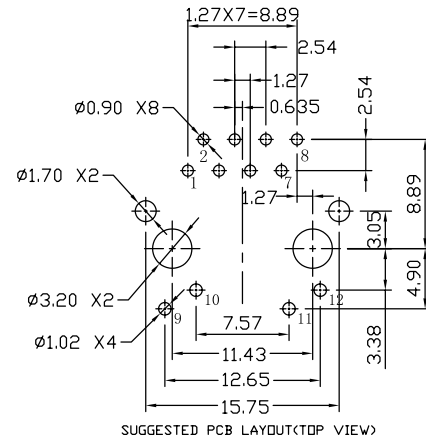
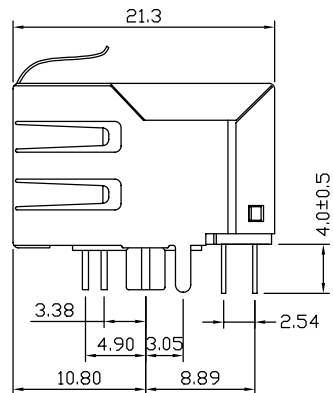
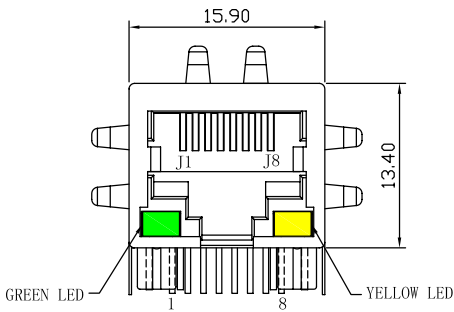
Cross Talk:

- 35dB Min @ 1.0-30MHz
- 35dB Min @ 30-60MHz
- 30dB Min @ 60-100MHz

Common Mode Rejection:

- 20dB Min @ 1.0-50MHz
- 15dB Min @ 50-100MHz

Hipot Test: 1500Vrms Min



General Tolerance	
.X ± 0.30	Angles: ±1°
.XX ± 0.20	
.XXX ± 0.05	
Units : mm	